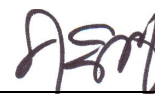


ASB Inc.
831 Tamnip-dong, Yuseong-gu, Daejeon 305-510, Korea

Part Number: Applicable to ASX-series, ASL-Series
Product Name: GaAs Amplifier
Package Type: SOIC-8

Package Elements	Constituents	CAS No.	Weight (mg)	Weight %
Active Semiconductor Die	GaAs	1303-00-0	0.589	100
Leadframe	Cu	7440-50-8	26.0091	97.442
	Fe	7439-89-6	0.6275	2.351
	P	7723-14-0	0.0220	0.082
	Zn	7440-66-6	0.0334	0.125
Leadframe Plating	Sn	7440-31-5	7.21	100
Epoxy Molding Compound	Silica Fused	60676-86-0	18.1575	80.700
	Epoxy Resin	129915-35-1	2.25	10.000
	Phenol Resin	26834-02-6	1.125	5.000
	Antimony Trioxide	1309-64-4	0.3375	1.500
	Brominated Epoxy Resin	68541-56-0	0.5625	2.500
	Carbon Black	1333-86-4	0.0675	0.300
Epoxy Resin	Silver	7440-22-4	13.838	74.000
	Epoxy Resin	129915-35-1	3.74	20.000
	Gamma-Butyrolactone	96-48-0	0.561	3.000
	Phenolic Resin	26834-02-6	0.561	3.000
Wire	Au	7440-57-5	8.54	100
Total			84.23	

This information sheet is to declare all substances intentionally added in our SOIC-8 semiconductor products. Total weight of the package varies depending on active die size. The material data is evidenced by written declaration from our packaging company. The products listed above DO NOT CONTAIN intentionally added hazardous materials such as cadmium (Cd), mercury (Hg), hexavalent chromium (Cr⁶⁺), polybrominated biphenyls (PBBs), and polybrominated diphenylethers (PBDEs) except for 0.001 wt.% of lead (Pb), which **COMPLY with the EU RoHS Directive 2002/95/EC and EU Commission Decision 2005/618/EC**. For further information, contact our Sales Department at sales@asb.co.kr.



Authorized Signature, ASB Inc.

This data is based on information provided by our suppliers and we do not validate it by measurement. ASB Inc. assumes no responsibility in connection with any use of this information. The information is subject to change without notice.
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